

立法會
Legislative Council

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Tel : 2869 9205

Date : 4 May 2009

From : Clerk to the Legislative Council

To : All Members of the Legislative Council

Council meeting of 20 May 2009

**Proposed resolution under
the Loans Ordinance**

I forward for Members' consideration a proposed resolution which the Financial Secretary will move at the Council meeting of 20 May 2009 under the Loans Ordinance. The President has directed that "it be printed in the terms in which it was handed in" on the Agenda of the Council.

2. The speech, in both English and Chinese versions, which the Financial Secretary will deliver when moving the proposed resolution, is also attached.

(Mrs Justina LAM)
for Clerk to the Legislative Council

Encl.

LOANS ORDINANCE

RESOLUTION

(Under section 3 of the Loans Ordinance (Cap. 61))

RESOLVED that –

- (a) the Government be authorized to borrow from any person from time to time for the purposes of the Bond Fund established by a resolution made and passed under section 29 of the Public Finance Ordinance (Cap. 2) such sums not exceeding in total \$100 billion or equivalent, being the maximum amount of all borrowings made under this paragraph that may be outstanding by way of principal at any time; and
- (b) sums borrowed under paragraph (a) are to be credited to the Bond Fund.

[DRAFT]

**SPEECH BY
THE FINANCIAL SECRETARY
IN THE LEGISLATIVE COUNCIL
ON 20 MAY 2009**

GOVERNMENT BOND PROGRAMME

LOANS ORDINANCE (CHAPTER 61)

Resolution to Authorize the Government to Borrow

President,

I move the motion standing in my name on the Agenda.

2. This resolution seeks to authorize the Government to borrow up to a ceiling of HK\$100 billion or equivalent in accordance with the Loans Ordinance.

3. First of all, I would like to thank Members for supporting the motion I have moved just now, which concerns the authorization for the Government to set up the “Bond Fund” under the Public Finance Ordinance to manage sums raised under the Government Bond Programme.

4. As I have mentioned earlier, implementation of the Government Bond Programme is an important step in promoting the development of the local bond market. Upon careful consideration of relevant factors, it is proposed that authorization be given to the Government to borrow up to a ceiling of HK\$100 billion or equivalent for the purpose of the “Bond Fund”. The relevant borrowing ceiling refers to the maximum amount of all borrowings that may be outstanding by way of principal at any time under the Programme,

i.e. principal amount of bonds issued minus that of bonds redeemed.

5. I would like to stress that the total size of the Programme is an important indicator for the market to assess the determination and effort of the Government in promoting the development of the local bond market. The proposed borrowing ceiling is reasonable and necessary. It fully reflects the long-term and on-going nature of the Programme and provides enough room for the public debt market to grow into a critical mass, thereby enabling the Programme to bring about its intended effect. The proposed borrowing ceiling represents a long-term target over a period of 5 to 10 years. It can provide the necessary flexibility for the Government to make necessary adjustments to the issuance size and tenor of individual tranches in response to market needs when implementing the Programme.

6. Upon the passage of this resolution by the Legislative Council, we will proceed full-steam ahead with the preparatory work for launching the Government Bond Programme within the confine of the relevant borrowing ceiling, including hammering out the parameters of the Programme such as the size of individual issues, tenor, frequency of issues, etc. We will solicit further market views in the process, and take into account relevant factors such as market conditions and impact on other issuers in the market before hammering out the relevant details.

7. President, I earnestly hope that Members will support the Resolution in order to facilitate early implementation the Government Bond Programme.

《End》